

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

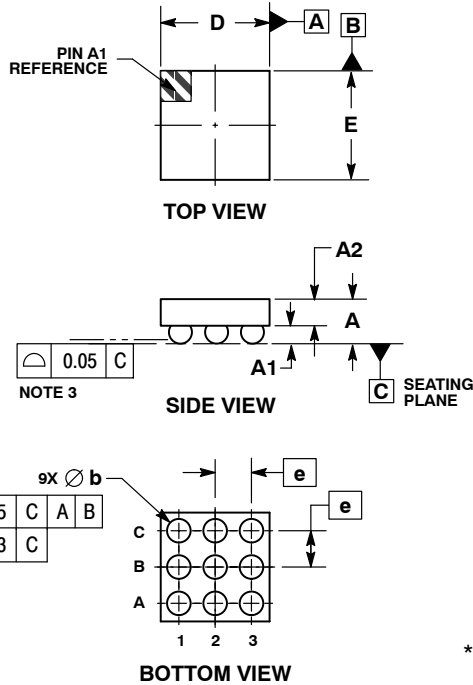
ON Semiconductor®



SCALE 4:1

WLCSP9, 1.2x1.2x0.48
CASE 567UL
ISSUE A

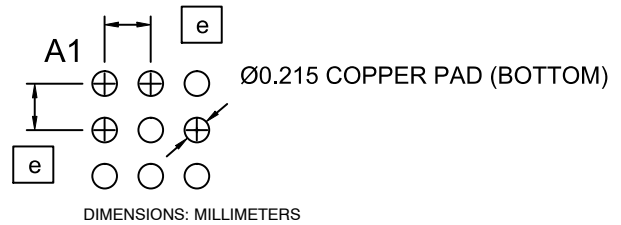
DATE 07 JUL 2017



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.450	0.488	0.526
A1	0.176	0.196	0.216
A2	0.274	0.292	0.310
b	0.24	0.26	0.28
D	1.14	1.20	1.26
E	1.14	1.20	1.26
e	0.40 BSC		

RECOMMENDED SOLDERING FOOTPRINT* (NSMD PAD TYPE)



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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